

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT4123889

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Kun-Ju Li	10/28/2016
Kuo-Chin Hung	10/28/2016
Min-Chuan Tsai	10/28/2016
Wei-Chuan Tsai	10/28/2016
Yi-Han Liao	10/28/2016
Chun-Tsen Lu	10/28/2016
Fu-Shou Tsai	10/28/2016
Li-Chieh Hsu	10/28/2016
RECEIVING PARTY DATA	
Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15340982
CORRESPONDENCE DATA	
Fax Number:	(703)997-4517
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	3027291562
Email:	Patent.admin.uspto.cr@naipo.com
Correspondent Name:	WINSTON HSU
Address Line 1:	P.O.BOX 506
Address Line 4:	MERRIFIELD, VIRGINIA 22116
ATTORNEY DOCKET NUMBER:	NAUP2845USA
NAME OF SUBMITTER:	KATE YEHL
SIGNATURE:	/KATE YEHL/
DATE SIGNED:	11/02/2016

Total Attachments: 16

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COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention:

CONDUCTIVE STRUCTURE, LAYOUT STRUCTURE INCLUDING CONDUCTIVE STRUCTURE, AND METHOD FOR MANUFACTURING CONDUCTIVE STRUCTURE

As the below named inventor, I hereby declare that:
This declaration is directed to:

- The attached application, or
- United States application number _____ filed on _____, or
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The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

In consideration of the payment by **UNITED MICROELECTRONICS CORP.** having a postal address of _____

No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City 300, Taiwan, R.O.C.

(referred to as "ASSIGNEE" below) to I of the sum of One Dollar (\$ 1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.

I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal

representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WINTNESS WHEREOF, I have hereunto set hand and seal this OCT 28 2016 (Date of signing)

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Kun-Ju Li**

Date: **OCT 28 2016**

Signature: Kun-Ju Li

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Kuo-Chin Hung**

Date: **OCT 28 2016**

Signature: Kuo-Chin Hung

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Min-Chuan Tsai**

Date: **OCT 28 2016**

Signature: Min Chuan Tsai

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Wei-Chuan Tsai**

Date: **OCT 28 2016**

Signature: Wei-Chuan Tsai

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Yi-Han Liao**

Date: **OCT 28 2016**

Signature: Yi - Han Liao

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Chun-Tsen Lu**

Date: **OCT 28 2016**

Signature: Chun-Tsen Lu

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Inventor: **Fu-Shou Tsai**

Date: **OCT 28 2016**

Signature: Fu Shou Tsai

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Inventor: **Li-Chieh Hsu**

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